

# 74LVC1G125

Bus buffer/line driver; 3-state

Rev. 11 — 2 July 2012

Product data sheet

## 1. General description

The 74LVC1G125 provides one non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input ( $\overline{OE}$ ). A HIGH-level at pin  $\overline{OE}$  causes the output to assume a high-impedance OFF-state.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- CMOS low power consumption
- Inputs accept voltages up to 5 V
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Multiple package options
- Specified from  $-40$  °C to  $+85$  °C and  $-40$  °C to  $+125$  °C



### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC1G125GW	−40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G125GV	−40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G125GM	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G125GF	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74LVC1G125GN	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74LVC1G125GS	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74LVC1G125GX	−40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

### 4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74LVC1G125GW	VM
74LVC1G125GV	V25
74LVC1G125GM	VM
74LVC1G125GF	VM
74LVC1G125GN	VM
74LVC1G125GS	VM
74LVC1G125GX	VM

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

### 5. Functional diagram

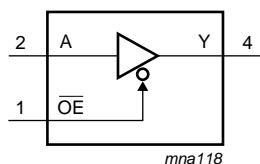


Fig 1. Logic symbol

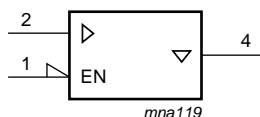


Fig 2. IEC logic symbol

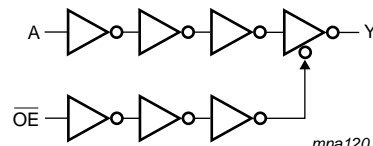
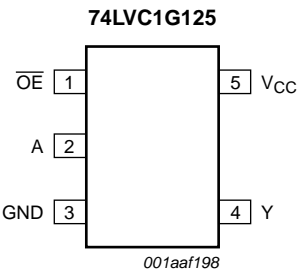


Fig 3. Logic diagram

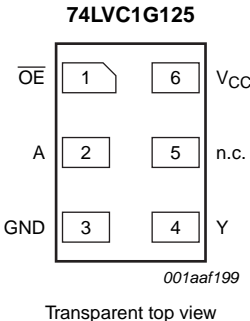
6. Pinning information

6.1 Pinning



74LVC1G125

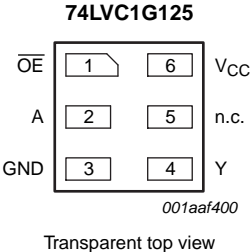
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74LVC1G125

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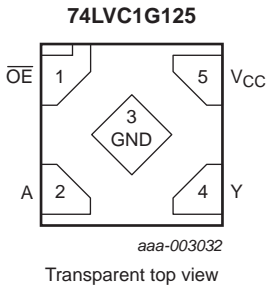
Transparent top view



74LVC1G125

001aaf400

Transparent top view



74LVC1G125

aaa-003032

Transparent top view

Fig 4. Pin configuration SOT353-1 and SOT753

Fig 5. Pin configuration SOT886

Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

Fig 7. Pin configuration SOT1226 (X2SON5)

6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
$\overline{\text{OE}}$	1	1	output enable input
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
OE	A	Y
L	L	L
L	H	H
H	X	Z

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 X = don't care;  
 Z = high-impedance OFF-state.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		<sup>[1]</sup> -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
$V_O$	output voltage	Active mode	<sup>[1][2]</sup> -0.5	$V_{CC} + 0.5$	V
		Power-down mode	<sup>[1][2]</sup> -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±50	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	<sup>[3]</sup> -	250	mW
$T_{stg}$	storage temperature		-65	+150	°C

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 [2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.  
 [3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
 For XSON6 and X2SON5 package: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	$V_{CC}$	V
		$V_{CC} = 0$ V; Power-down mode	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	-	-	20	ns/V
		$V_{CC} = 2.7$ V to 5.5 V	-	-	10	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
<b><math>T_{amb} = -40</math> °C to <math>+85</math> °C</b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	V
		$V_{CC} = 4.5$ V to 5.5 V	$0.7 \times V_{CC}$	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	V
		$V_{CC} = 4.5$ V to 5.5 V	-	-	$0.3 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65$ V to 5.5 V; $I_O = 100$ $\mu$ A	-	-	0.1	V
		$V_{CC} = 1.65$ V; $I_O = 4$ mA	-	-	0.45	V
		$V_{CC} = 2.3$ V; $I_O = 8$ mA	-	-	0.3	V
		$V_{CC} = 2.7$ V; $I_O = 12$ mA	-	-	0.4	V
		$V_{CC} = 3.0$ V; $I_O = 24$ mA	-	-	0.55	V
		$V_{CC} = 4.5$ V; $I_O = 32$ mA	-	-	0.55	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65$ V to 5.5 V; $I_O = -100$ $\mu$ A	$V_{CC} - 0.1$	-	-	V
		$V_{CC} = 1.65$ V; $I_O = -4$ mA	1.2	-	-	V
		$V_{CC} = 2.3$ V; $I_O = -8$ mA	1.9	-	-	V
		$V_{CC} = 2.7$ V; $I_O = -12$ mA	2.2	-	-	V
		$V_{CC} = 3.0$ V; $I_O = -24$ mA	2.3	-	-	V
		$V_{CC} = 4.5$ V; $I_O = -32$ mA	3.8	-	-	V
$I_I$	input leakage current	$V_{CC} = 0$ V to 5.5 V; $V_I = 5.5$ V or GND	-	$\pm 0.1$	$\pm 5$	$\mu$ A
$I_{OZ}$	OFF-state output current	$V_{CC} = 3.6$ V; $V_I = V_{IH}$ or $V_{IL}$ ; $V_O = 5.5$ V or GND	-	$\pm 0.1$	$\pm 10$	$\mu$ A

**Table 7.** Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ <sup>[1]</sup>	Max	Unit
$I_{OFF}$	power-off leakage current	$V_{CC} = 0\text{ V}$ ; $V_I$ or $V_O = 5.5\text{ V}$	-	$\pm 0.1$	$\pm 10$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = 5.5\text{ V}$ or GND; $V_{CC} = 1.65\text{ V}$ to $5.5\text{ V}$ ; $I_O = 0\text{ A}$	-	0.1	10	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per pin; $V_{CC} = 2.3\text{ V}$ to $5.5\text{ V}$ ; $V_I = V_{CC} - 0.6\text{ V}$ ; $I_O = 0\text{ A}$	-	5	500	$\mu\text{A}$
$C_I$	input capacitance		-	5	-	pF
<b><math>T_{amb} = -40\text{ }^{\circ}\text{C}</math> to <math>+125\text{ }^{\circ}\text{C}</math></b>						
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65\text{ V}$ to $1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3\text{ V}$ to $2.7\text{ V}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	2.0	-	-	V
		$V_{CC} = 4.5\text{ V}$ to $5.5\text{ V}$	$0.7 \times V_{CC}$	-	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65\text{ V}$ to $1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V}$ to $2.7\text{ V}$	-	-	0.7	V
		$V_{CC} = 2.7\text{ V}$ to $3.6\text{ V}$	-	-	0.8	V
		$V_{CC} = 4.5\text{ V}$ to $5.5\text{ V}$	-	-	$0.3 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65\text{ V}$ to $5.5\text{ V}$ ; $I_O = 100\text{ }\mu\text{A}$	-	-	0.1	V
		$V_{CC} = 1.65\text{ V}$ ; $I_O = 4\text{ mA}$	-	-	0.70	V
		$V_{CC} = 2.3\text{ V}$ ; $I_O = 8\text{ mA}$	-	-	0.45	V
		$V_{CC} = 2.7\text{ V}$ ; $I_O = 12\text{ mA}$	-	-	0.60	V
		$V_{CC} = 3.0\text{ V}$ ; $I_O = 24\text{ mA}$	-	-	0.80	V
		$V_{CC} = 4.5\text{ V}$ ; $I_O = 32\text{ mA}$	-	-	0.80	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$				
		$V_{CC} = 1.65\text{ V}$ to $5.5\text{ V}$ ; $I_O = -100\text{ }\mu\text{A}$	$V_{CC} - 0.1$	-	-	V
		$V_{CC} = 1.65\text{ V}$ ; $I_O = -4\text{ mA}$	0.95	-	-	V
		$V_{CC} = 2.3\text{ V}$ ; $I_O = -8\text{ mA}$	1.7	-	-	V
		$V_{CC} = 2.7\text{ V}$ ; $I_O = -12\text{ mA}$	1.9	-	-	V
		$V_{CC} = 3.0\text{ V}$ ; $I_O = -24\text{ mA}$	2.0	-	-	V
		$V_{CC} = 4.5\text{ V}$ ; $I_O = -32\text{ mA}$	3.4	-	-	V
$I_I$	input leakage current	$V_{CC} = 0\text{ V}$ to $5.5\text{ V}$ ; $V_I = 5.5\text{ V}$ or GND	-	-	$\pm 100$	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	$V_{CC} = 3.6\text{ V}$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $V_O = 5.5\text{ V}$ or GND	-	-	$\pm 200$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_{CC} = 0\text{ V}$ ; $V_I$ or $V_O = 5.5\text{ V}$	-	-	$\pm 200$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = 5.5\text{ V}$ or GND; $V_{CC} = 1.65\text{ V}$ to $5.5\text{ V}$ ; $I_O = 0\text{ A}$	-	-	200	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per pin; $V_{CC} = 2.3\text{ V}$ to $5.5\text{ V}$ ; $V_I = V_{CC} - 0.6\text{ V}$ ; $I_O = 0\text{ A}$	-	-	5000	$\mu\text{A}$

[1] All typical values are measured at  $V_{CC} = 3.3\text{ V}$  and  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	A to Y; see <a href="#">Figure 8</a> <a href="#">[2]</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	3.3	8.0	1.0	10.5	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.2	5.5	0.5	7	ns
		V <sub>CC</sub> = 2.7 V	0.5	2.5	5.5	0.5	7	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	2.1	4.5	0.5	6	ns
t <sub>en</sub>	enable time	OE to Y; see <a href="#">Figure 9</a> <a href="#">[3]</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.1	9.4	1.0	12	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.8	6.6	0.5	8.5	ns
		V <sub>CC</sub> = 2.7 V	0.5	3.3	6.6	0.5	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	2.4	5.3	0.5	7	ns
t <sub>dis</sub>	disable time	OE to Y; see <a href="#">Figure 9</a> <a href="#">[4]</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	4.3	9.2	1.0	12	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.5	2.7	5.0	0.5	6.5	ns
		V <sub>CC</sub> = 2.7 V	0.5	3.0	5.0	0.5	6.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.5	3.1	5.0	0.5	6.5	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; V <sub>I</sub> = GND to V <sub>CC</sub> <a href="#">[5]</a>						
		output enabled	-	25	-	-	-	pF
		output disabled	-	6	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>

[3] t<sub>en</sub> is the same as t<sub>PZH</sub> and t<sub>PZL</sub>

[4] t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>

[5] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

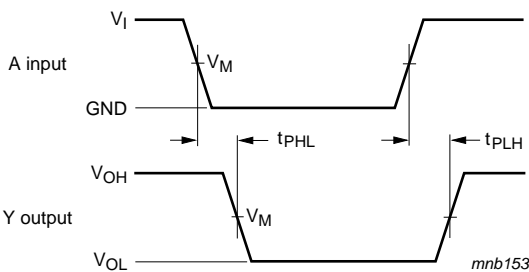
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

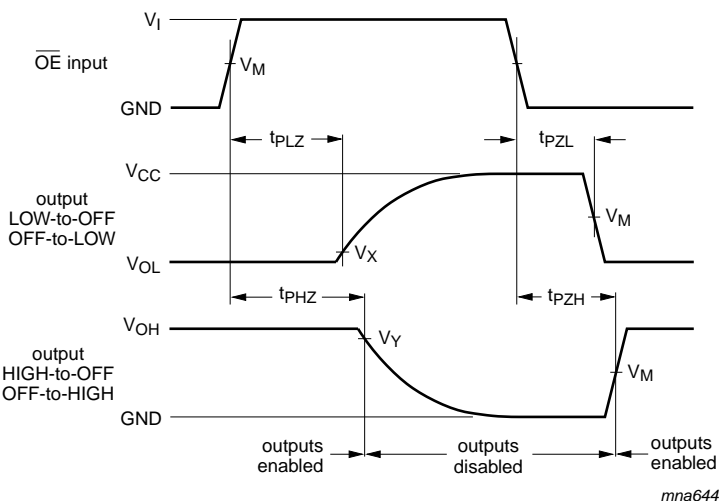
Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

12. Waveforms



Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. Input A to output Y propagation delay times**



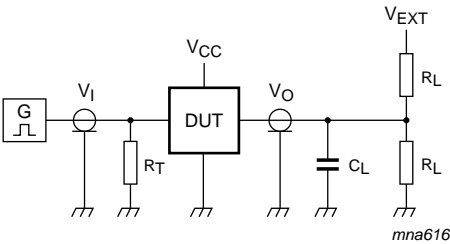
Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 9. 3-state enable and disable times**

**Table 9. Measurement points**

Supply voltage	Input	Output		
$V_{CC}$	$V_M$	$V_M$	$V_X$	$V_Y$
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15\text{ V}$	$V_{OH} - 0.15\text{ V}$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15\text{ V}$	$V_{OH} - 0.15\text{ V}$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$
4.5 V to 5.5 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$





Test data is given in [Table 10](#).  
Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = External voltage for measuring switching times.

Fig 10. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>		
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	1 kΩ	open	GND	2V <sub>CC</sub>
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	500 Ω	open	GND	2V <sub>CC</sub>
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	GND	6 V
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	GND	6 V
4.5 V to 5.5 V	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Ω	open	GND	2V <sub>CC</sub>

13. Package outline

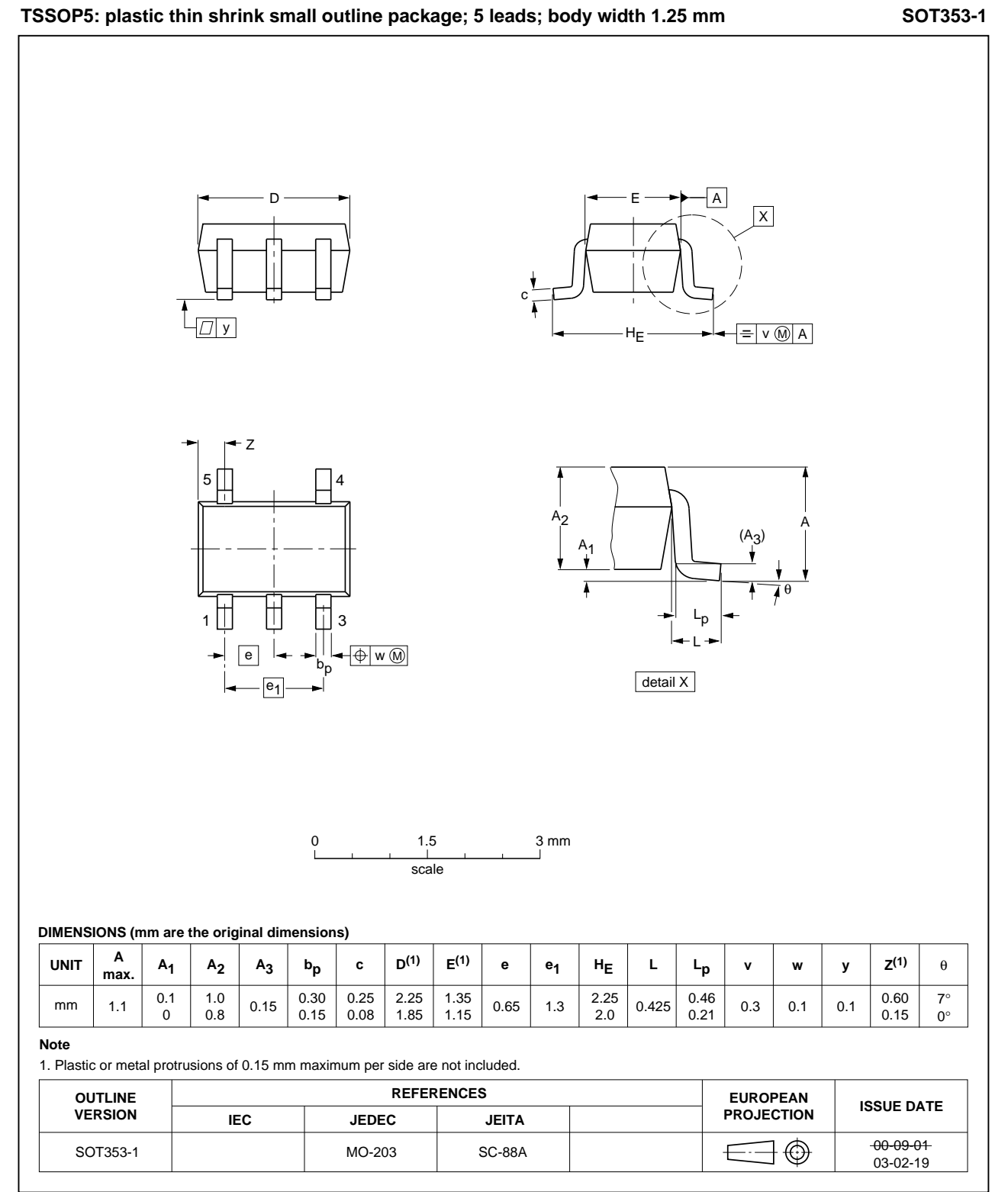


Fig 11. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

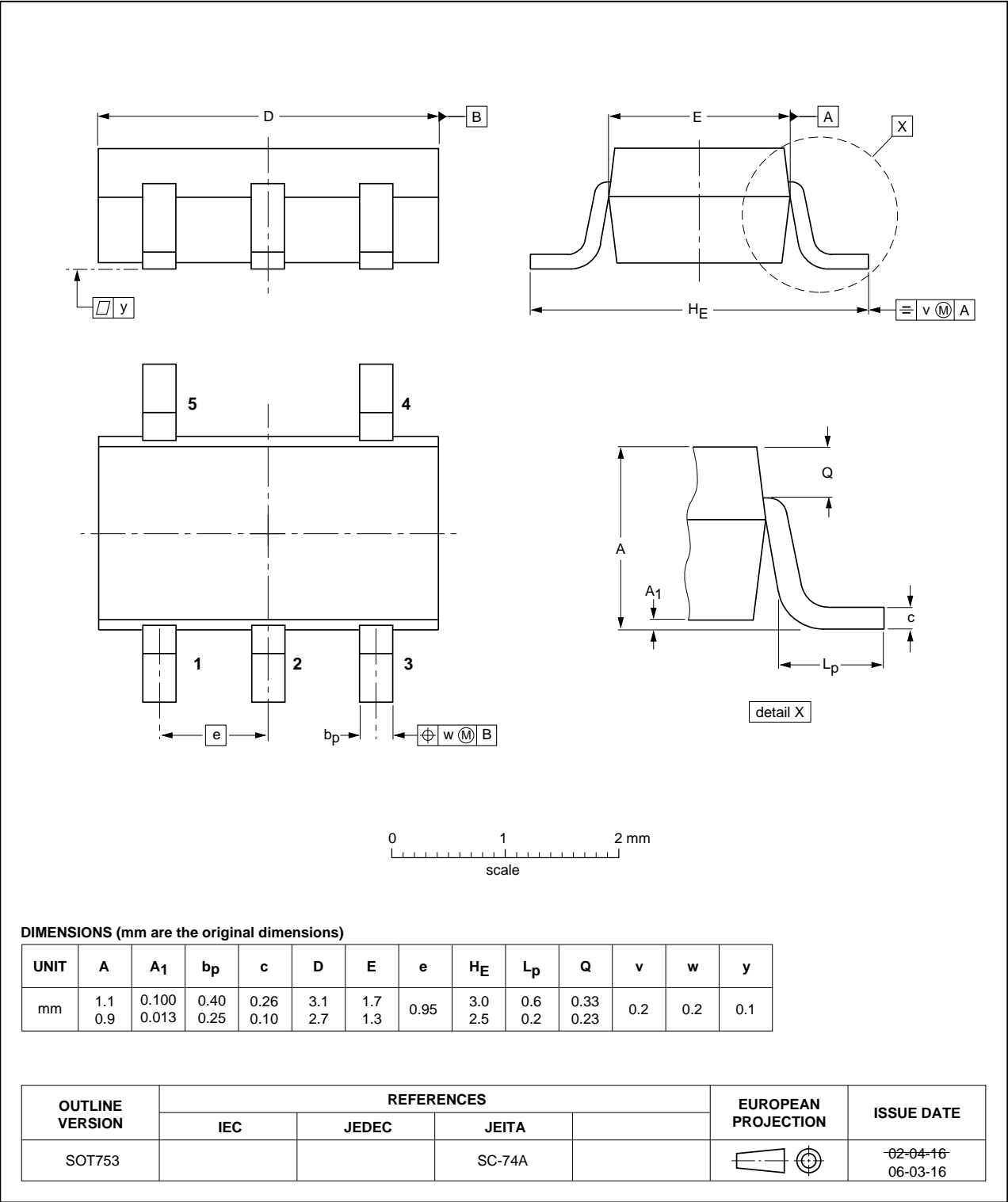


Fig 12. Package outline SOT753

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

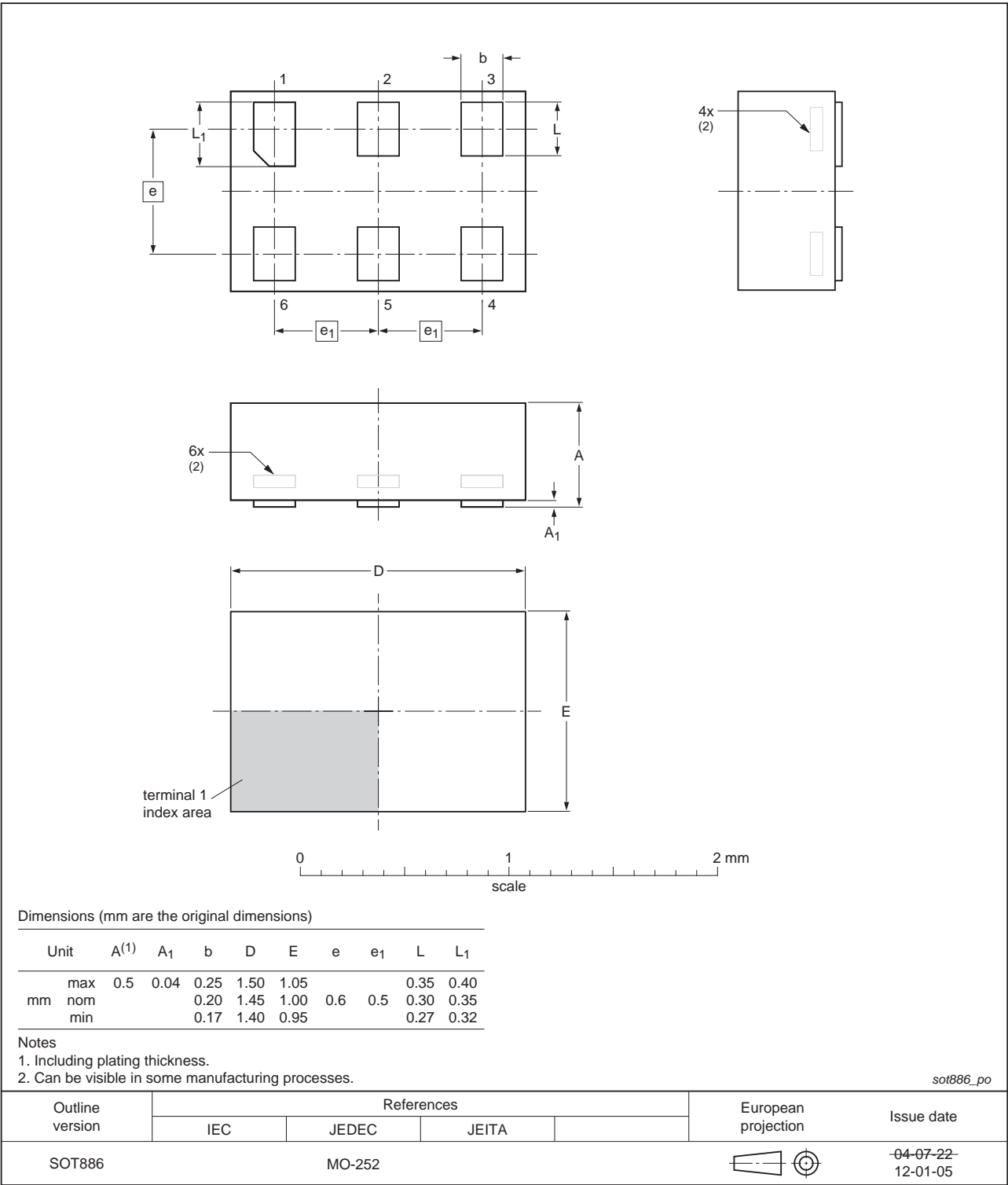
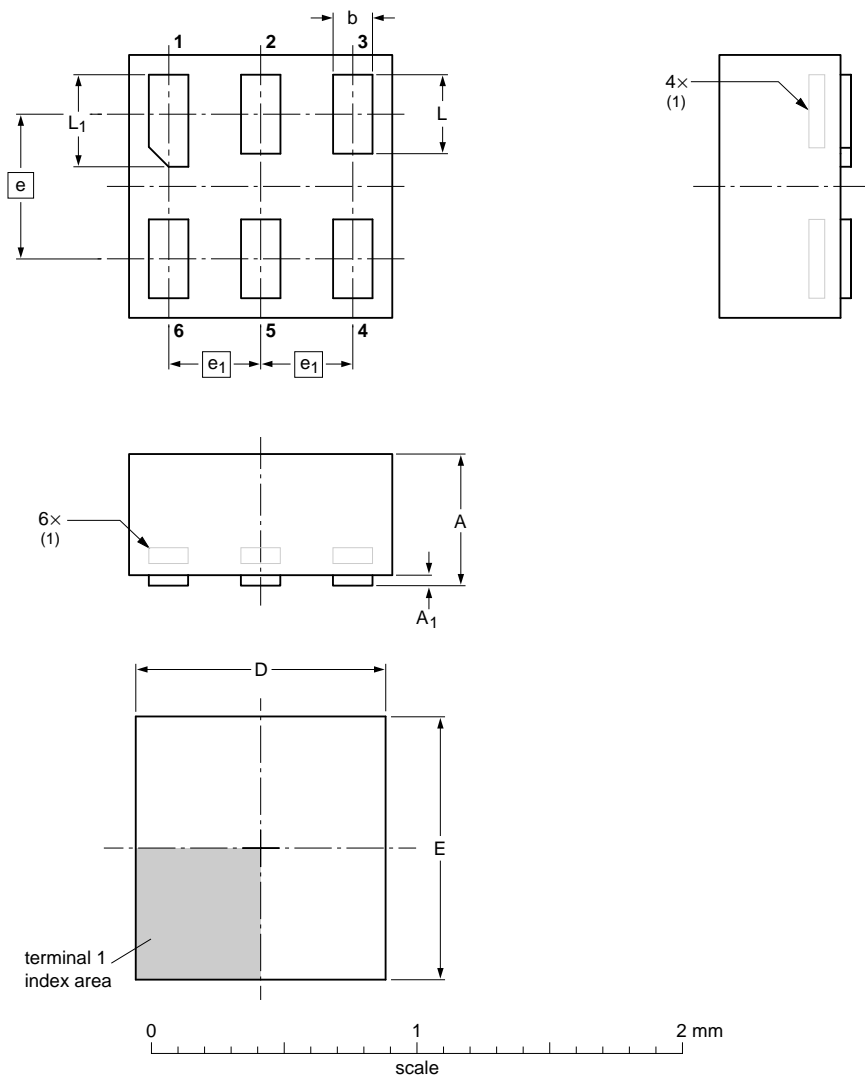


Fig 13. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891



DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1max</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	0.5	0.04	0.20 0.12	1.05 0.95	1.05 0.95	0.55	0.35	0.35 0.27	0.40 0.32

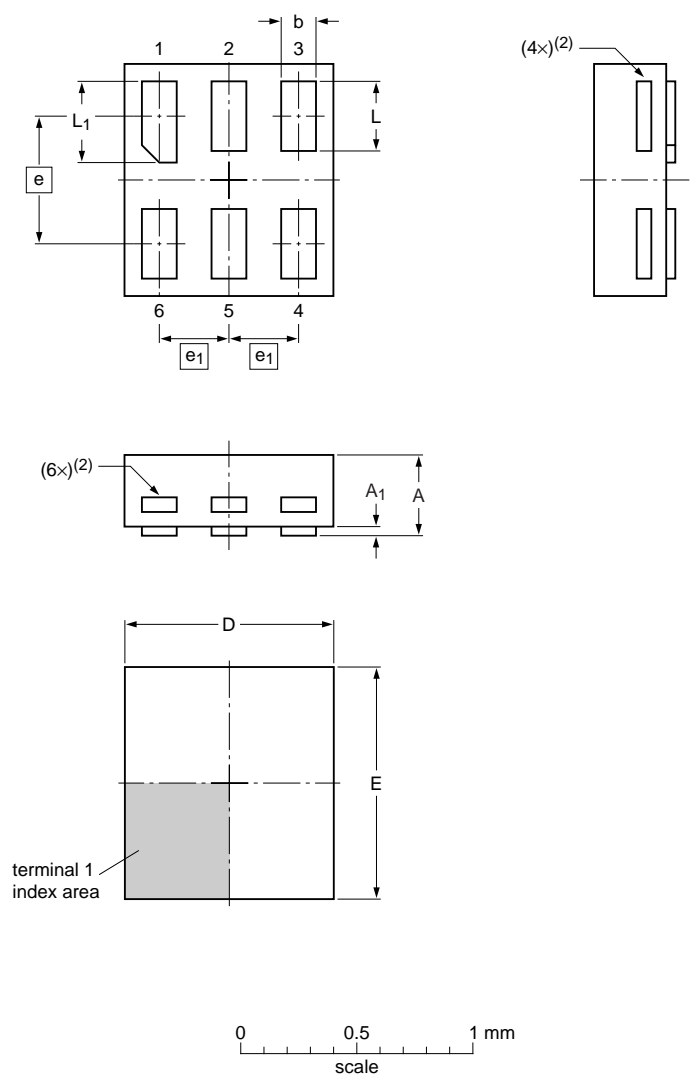
Note  
1. Can be visible in some manufacturing processes.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT891						05-04-06 07-05-15

Fig 14. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max	0.35	0.04	0.20	0.95	1.05		0.35	0.40
	nom			0.15	0.90	1.00	0.55	0.30	0.35
	min			0.12	0.85	0.95		0.27	0.32

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1115\_po

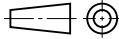
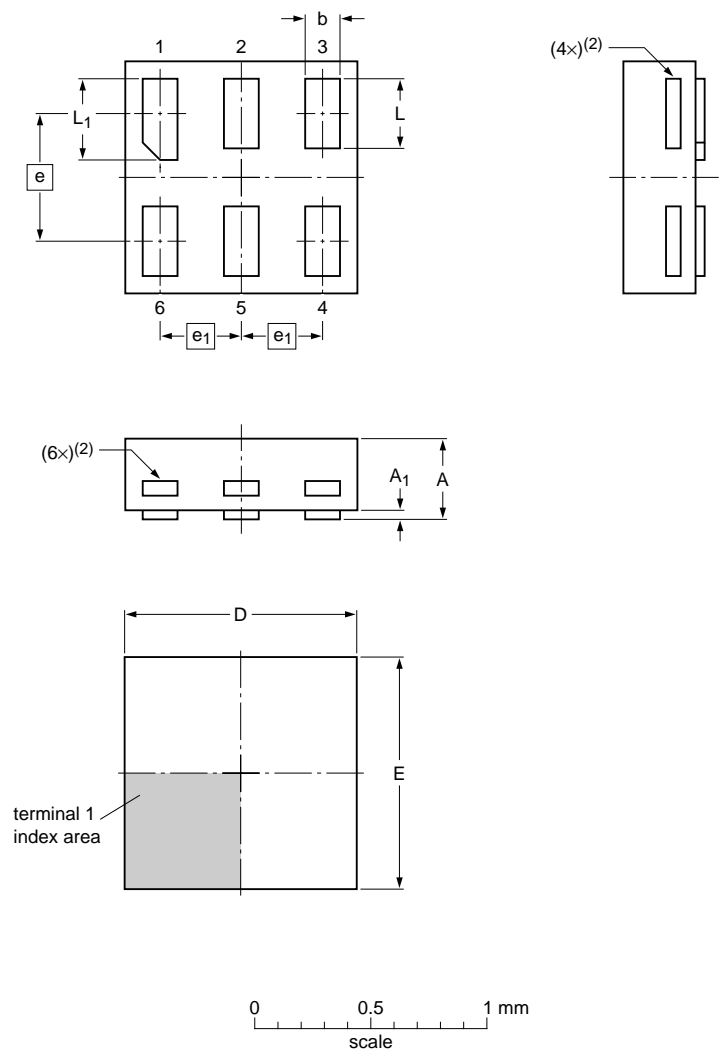
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1115						<del>10-04-02</del> 10-04-07

Fig 15. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max	0.35	0.04	0.20	1.05	1.05		0.35	0.40
	nom			0.15	1.00	1.00	0.55	0.30	0.35
	min			0.12	0.95	0.95		0.27	0.32

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1202\_po

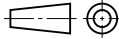
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1202						<del>10-04-02</del> 10-04-06

Fig 16. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

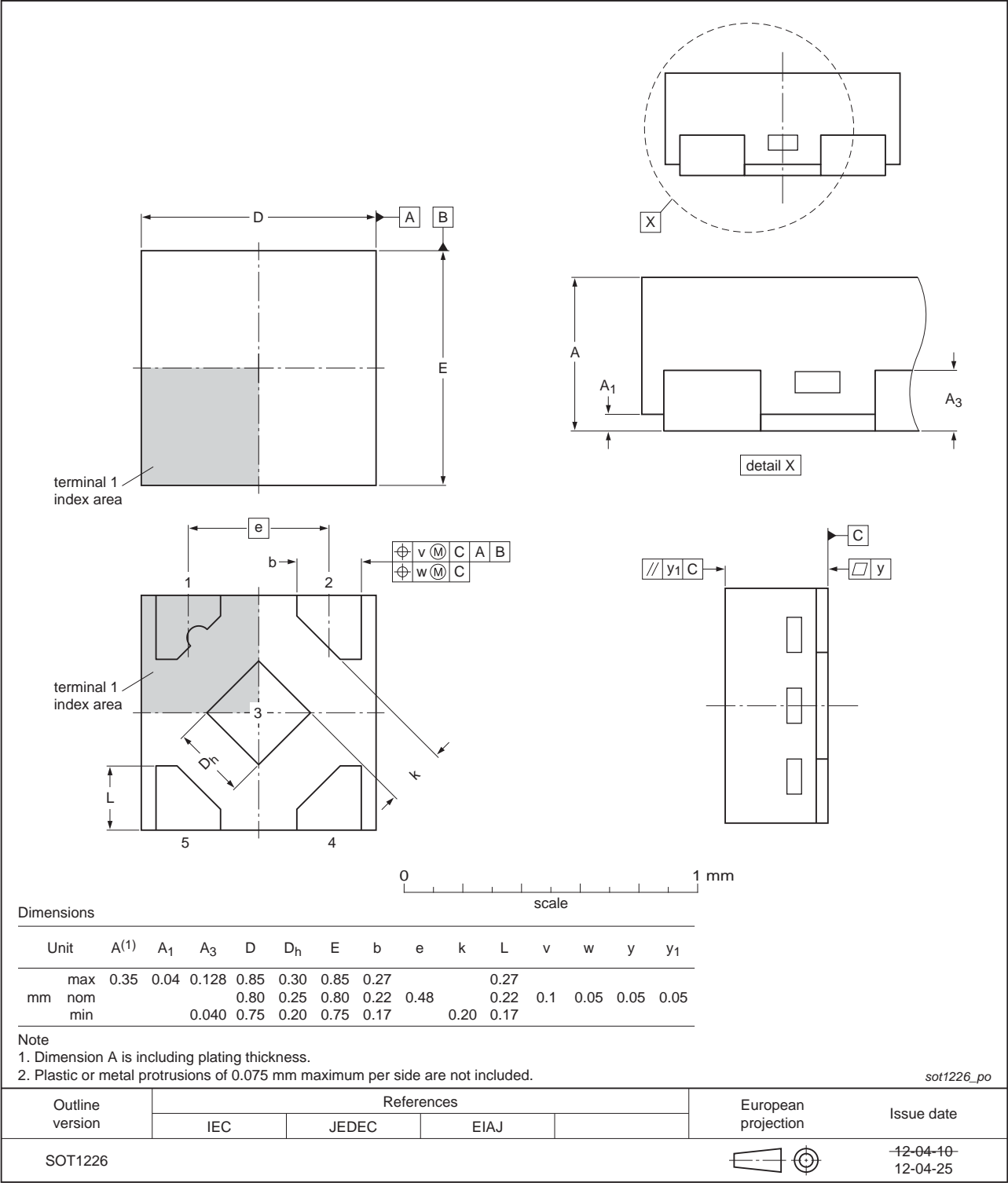


Fig 17. Package outline SOT1226 (X2SON5)



## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G125 v.11	20120702	Product data sheet	-	74LVC1G125 v.10
Modifications:	<ul style="list-style-type: none"><li>Added type number 74LVC1G125GX (SOT1226)</li><li>Package outline drawing of SOT886 (<a href="#">Figure 13</a>) modified.</li></ul>			
74LVC1G125 v.10	20111207	Product data sheet	-	74LVC1G125 v.9
Modifications:	<ul style="list-style-type: none"><li>Legal pages updated.</li></ul>			
74LVC1G125 v.9	20101229	Product data sheet	-	74LVC1G125 v.8
74LVC1G125 v.8	20100824	Product data sheet	-	74LVC1G125 v.7
74LVC1G125 v.7	20070830	Product data sheet	-	74LVC1G125 v.6
74LVC1G125 v.6	20060912	Product data sheet	-	74LVC1G125 v.5
74LVC1G125 v.5	20040915	Product specification	-	74LVC1G125 v.4
74LVC1G125 v.4	20021118	Product specification	-	74LVC1G125 v.3
74LVC1G125 v.3	20020528	Product specification	-	74LVC1G125 v.2
74LVC1G125 v.2	20010406	Product specification	-	74LVC1G125 v.1
74LVC1G125 v.1	20001222	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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